

About CITC

**Innovation
for
Tomorrow**

Who

- Independent R&D center founded in 2019
- Located on Novio Tech Campus, Nijmegen, The Netherlands

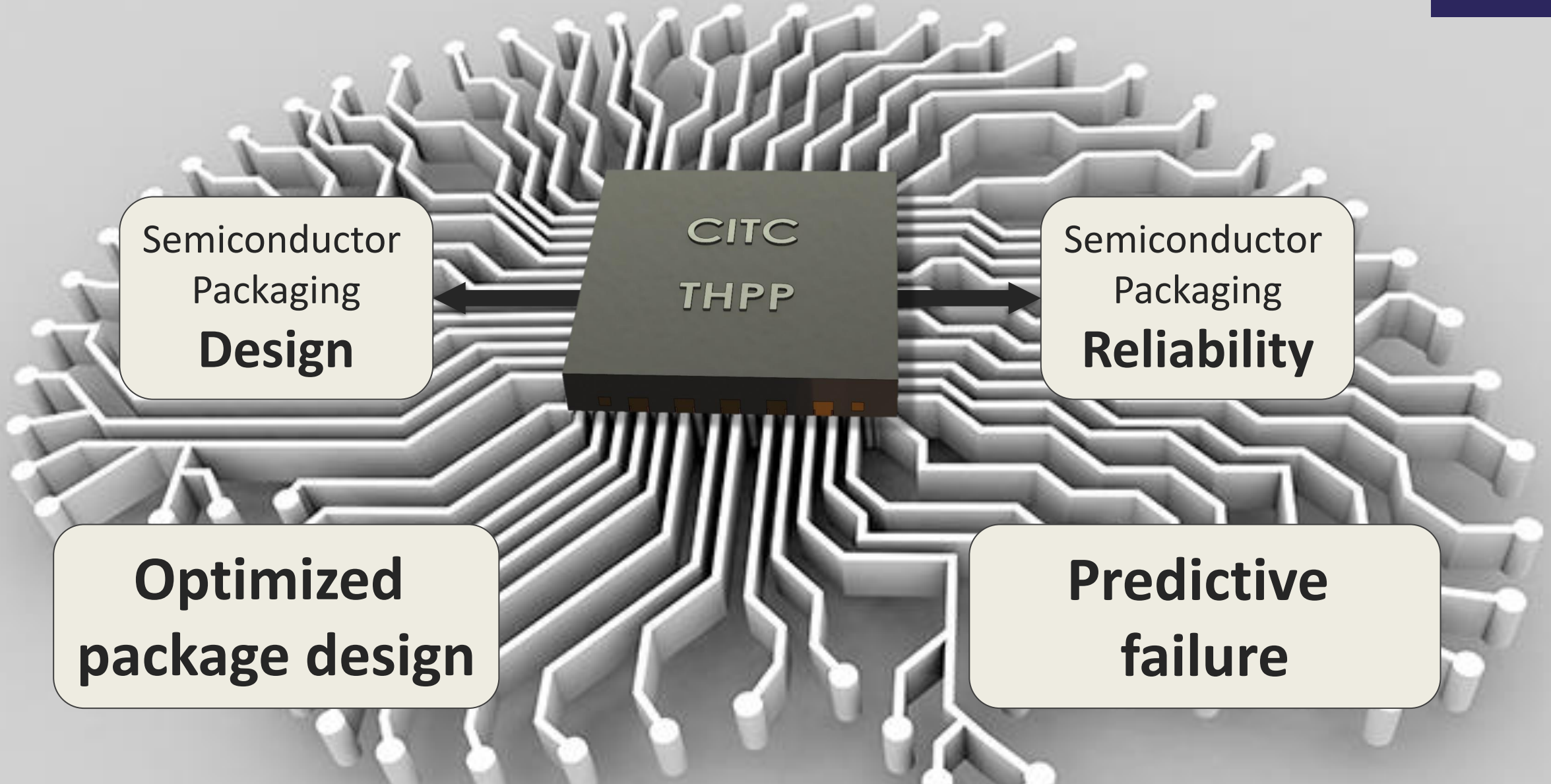
Why

- Integration and packaging technology growing in importance
- Need from industry to co-develop new technology

What

- Provide access to innovation, infrastructure & education
- Current application areas Power, RF and Photonic integration
- Develop innovative packaging solutions

AI for Semiconductor Packaging



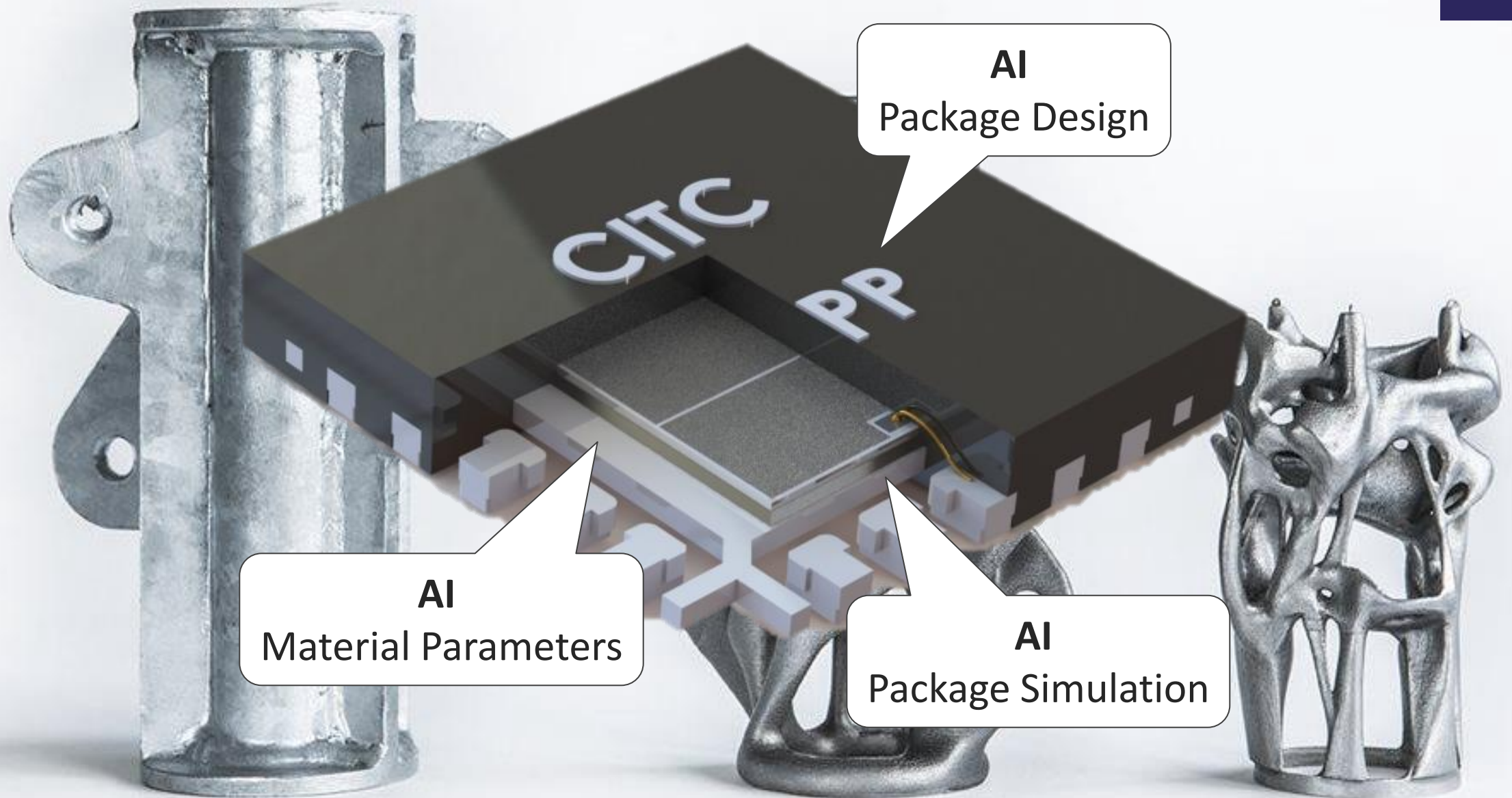
Semiconductor Packaging
Design

Semiconductor Packaging
Reliability

**Optimized
package design**

**Predictive
failure**

AI for Semiconductor Packaging design

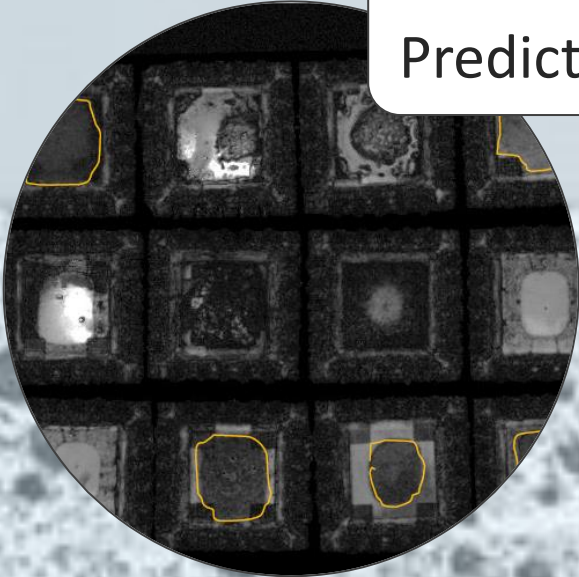


AI
Package Design

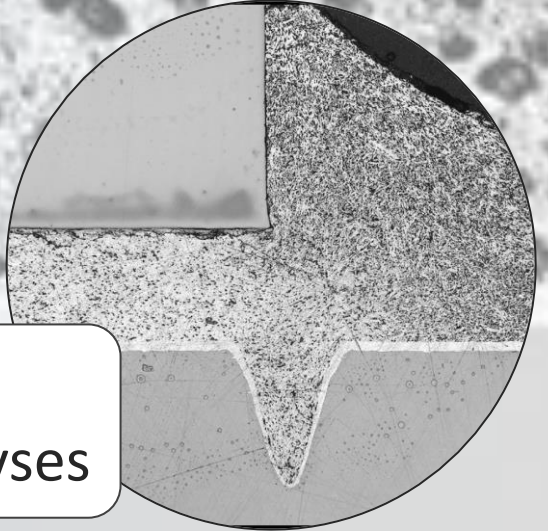
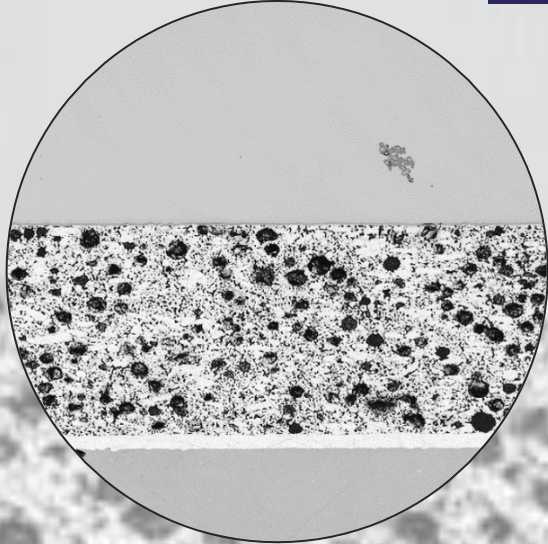
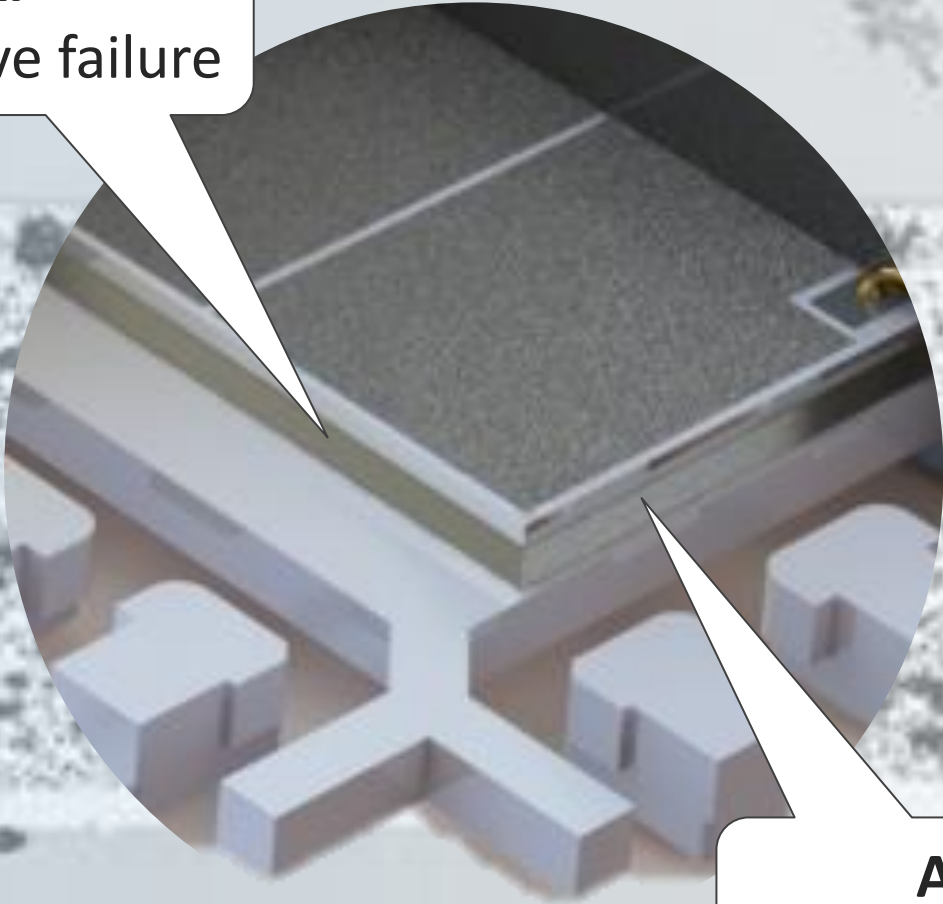
AI
Material Parameters

AI
Package Simulation

AI for Failure mode analyses



AI
Predictive failure



AI
Failure analyses

Question

Can AI help us **Semiconductor Packaging**

Optimized design of chip packages, design for performance and design for reliability

Detect artifacts in the package and differentiate the type and location and depth of failure?

